

# Glass 8360

## Technical Data

GlassType/Application	Soft glass, lead-free Encapsulation of semiconductor components at low temperature (diodes)		
Physical Data (approx. value)	Coefficient of mean linear thermal expansion		
	$\alpha(20^{\circ}\text{C}; 300^{\circ}\text{C})$ (ISO 7991) .....	9.1	$10^{-6}\text{K}^{-1}$
	Transformation temperature $T_g$ (ISO 7884-8).....	465	$^{\circ}\text{C}$
	Glass temperature at viscosity $\eta$ in $\text{dPa}\cdot\text{s}$		
	$10^{13}$ (annealing point) (ISO 7884-4).....	470	$^{\circ}\text{C}$
	$10^{7.6}$ (softening point) (ISO 7884-3).....	575	$^{\circ}\text{C}$
	$10^4$ (working point) (ISO 7884-2).....	745	$^{\circ}\text{C}$
	Stress-optical coefficient $K$ (DIN 52314).....	2.9	$10^{-6}\text{mm}^2\cdot\text{N}^{-1}$
	Density $\rho$ at $25^{\circ}\text{C}$ .....	2.66	$\text{g}\cdot\text{cm}^{-3}$
	Modulus of elasticity $E$ (Young's modulus) .....	85	$10^3\text{N}\cdot\text{mm}^{-2}$
	Poisson's ratio $\mu$ .....	0.238	
	Thermal conductivity $\lambda_w$ at $90^{\circ}\text{C}$ .....	-	$\text{W}\cdot\text{m}^{-1}\cdot\text{K}^{-1}$
	Log of the electric volume resistivity ( $\Omega\cdot\text{cm}$ )		
	at $250^{\circ}\text{C}$ .....	8.5	
	at $350^{\circ}\text{C}$ .....	6.7	
	$t_{k100}$ .....	275	$^{\circ}\text{C}$
	Dielectric constant $\varepsilon$ for 1 MHz at $25^{\circ}\text{C}$ .....	7.3	
	Dielectric loss factor $\tan \delta$ for 1 MHz at $25^{\circ}\text{C}$ .....	24	$10^{-4}$
	Refractive index $n_d$ ( $\lambda = 587.6 \text{ nm}$ ) .....	1.566	
Chemical Resistance	Hydrolytic resistance (ISO 719) .....	Class	HGB 3
	Acid resistance (DIN 12116) .....	Class	S 4
	Alkali resistance (ISO 695) .....	Class	A 3
	The heavy metal content for the elements lead, cadmium, mercury and hexavalent chromium is below 100 ppm		